

**Minutes of the CE-2.0 National Connectors Standards Committee  
28 – 29 September 2010  
Austin, TX**

Members Present				
Name	Organization or Company	Meeting Present		
		September 2010	April 2010	October 2009
David Benfer	Tyco Electronics	X	X	
David Bouzek	Tri-Star Electronics	X	X	X
Don Chambers	Northrop-Grumman	X	X	X
H. John Healey	IBM	X	X	
Kevin Rickard	Amphenol	X	X	X
Frank Ruffino (Chairman)	Molex Inc.	X	X	X
Ed Wypasek	DSCC-VAI	X	X	X
Carl Fritz (Vice Chairman)	Contech Research	X	X	X
Members Absent				
Bob Druckenmiller	FCI	-	X	X
Guest				
Others Present				
Ed Mikoski	ECA Staff	X	X	X

Meeting Number 47 of the National Connectors and Sockets Standards Committee convened at 8:00 AM on 28 September 2010 by Vice Chairman Carl Fritz. It was noted that for the purpose of this meeting a quorum was met. Bob Druckenmiller sent apologies for not being able to attend due to medical conditions. Chairman Frank Ruffino notified Vice Chairman that that he would be arriving late and apologized for the delay.

It is noted that the CE-2.0 committee will simultaneously approve all the actions taken by the subcommittees.

**1. Approval of the 27 – 28 April 2010 minutes**

The minutes of meeting No. 46 held in Orlando, FL were unanimously moved and approved. The motion was made by John Healey and seconded by Kevin Rickard.

## 2. CHAIRMAN'S REPORT AND ANNOUNCEMENTS (Frank Ruffino, Chairman)

Carl reviewed the current EIA Contact Listing with the committee and will revise it based on this meeting. It should be noted that this is only a contact list and not an EIA member listing. The membership list posted on the web site was reviewed and noted that Alan Davis should be moved to the non-voting member list.

(See Attachment No. 1 for current contact list).

## 3. SUBCOMMITTEE MEETINGS

### A. CE-2.1 Test Procedures (Chairman: Carl Fritz; Vice Chairman, Max Peel)

Carl Fritz convened the test procedures subcommittee.

(See Attachment No. 2 for CE-2.1 report).

### B. CE-2.3 Contact Specifications (was subcommittee CE-2.6) (Chairman: Dave Bouzek)

David Bouzek reported that there has been no action taken by SAE relating to the NAVAIR testing requirement. Any decision is currently on hold.

### C. CE-2.4 Editing Subcommittee (was subcommittee CE-2.7) (Chairman: Carl Fritz)

### D. CE-2.5 International Standards Subcommittee (was subcommittee CE-2.8) (Chairman: Jeff Toran)

It was noted that the next meeting will be held in Seattle, WA the week of October 10. Jeff Toran indicated that he will provide a report following the meeting, and include them with the minutes.

(See Attachment No. 3 for IEC report).

## 4. UL SAFETY UPDATE

Frank presented an update and basically indicated that UL has agreed to revert to the old system that has been in place for years. UL 1977 has been revised to use the electrical RTI as the maximum temperature, as was the requirement in previous revisions. UL is going to establish an adhoc committee to review the requirements in UL1977, and end use standards with the purpose of correlating the requirements. Frank asked anyone that is interested in participating in the adhoc committee to notify him.

## **5. CONNECTOR AND SOCKET DETAIL SPECIFICATIONS**

### **A. SP-4970, EIA-540DAAA-A, Detail, DIP**

This will be reissued as a new ballot.

### **B. SP-4971, EIA-700A0AB, 68-pin Memory Card Connector**

This will be reissued as a new ballot.

### **C. SP-5112 as follows:**

- EIA-700A0AC: Detail, 88-pin DRAM Connector
- EIA-540A000-A: Sectional, Chip Carrier Sockets
- EIA-540AA00: Blank, Leadless Chip Carrier Sockets
- EIA-540AAAA: Detail, Type A Chip Carrier Sockets
- EIA-540AB00: Blank, PQFP
- EIA-540ABAA: Detail, PQFP
- EIA-540AC00: Blank, PCC
- EIA-540ACAA: Detail, PCC
- EIA-540AD00: Blank, Adaptor QFP to PGA
- EIA-540B000: Sectional, PGA
- EIA-540BA00: Blank, PGA
- EIA-540BAAB: Detail, Non-Mechanical PGA
- EIA-540BAAC: Detail, Flex Carrier PGA
- EIA-540D000-A: Sectional, In-Line Packages
- EIA-540DA00: Blank, DIP (Will be sent out for review)
- EIA-540DAAB: Detail, Flex Carrier DIP
- EIA-540EA00: Blank, Round Sockets
- EIA-540EAAA: Detail, Round Sockets
- EIA-540F000: Sectional, Multi-Package Modules

This will be reissued as a new ballot.

**D. New Specification for Mini-Change A-Size (2-6 pole) Connector (Frank Ruffino)**

Frank reported that a draft will be sent out before the next meeting.

It was moved by Frank Ruffino and seconded by John Healey to obtain a project number to create a new specification, and send to EIA for a letter ballot or SP ballot at the discretion of the project leader. The motion was unanimously approved. It was also unanimously moved and approved that if there are sufficient ballots and no rejections received that the specification be sent to EIA for EDEC ballot for publication as an EIA Specification. In addition the specification should also be submitted to ANSI for publication as an American National Standard. It is also agreed that if the project leader receives editorial or technical comments, and no rejections, that the document may be revised and submitted for a subsequent ballot.

**E. Connector and Socket Specification Status**

Carl Fritz gave a presentation on the status of all connector and socket specification that he extracted from the EIA database that appear to be the responsibility of CE-2.0. He will coordinate review of the accuracy with EIA. The following tables reflect his findings.

**Connector Specifications Past Due for 5-Year Review**

EIA	Rev	Title	Date of last issue	5 Year due date	Years past due
270		Tools, Crimping, Solderless Wiring Devices - Recommended Procedures for User Certification	January-62	December-66	42
297	A	Cable Connectors for Audio Facilities for Radio Broadcasting-Correction Sheet	June-70	May-75	34
406		General Document for Connectors, Electric, Printed-Wiring Board-IPC-C-405A	January-74	December-78	30
429		Connectors, Electrical Flat Cable Type-IPC FC-218B	January-76	December-80	28
380	A	Electrical Connectors, Small Contact Standard for	January-78	December-82	26
IS-47		Contact Termination Finish Standard for Surface Mount Devices	July-87	June-92	17
IS-84		Interim Detail Specification for 2.5 mm Two Part Connector for Use in Electronic Equipment	April-92	April-97	12
280	C	Solderless Wrapped Electrical Connections	May-92	May-97	12
700A0AA		Detail Specification for 1.27 mm Pitch, Ribbon Contact, Trapezoidal Shaped, Shielded I/O Connector	April-96	April-01	8
700AAAB	A	Detail Specification for 1.0 mm, Two-Part Connectors for Use with Parallel Printed Boards	January-96	December-00	8
700C000		Sectional Specification for Circular Multicontact Connectors of Assessed Quality (for Frequencies Essentially Below 3 MHz)	January-97	January-02	7

**Connector Specifications Past Due for 5-Year Review**

EIA	Rev	Title	Date of last issue	5 Year due date	Years past due
7000000	A	Generic Specification for Electronic and Electrical Connectors of Certified Quality (for Frequencies Essentially Below 3 MHz)	August-96	July-01	7
IS-753		Two-Part High Density Blade and Backplane Tuning Fork Connector	February-98	February-03	6
700A0AD		Detail Specification for the Interface of the 1.27 mm Pitch, Ribbon Contact (Leaf Spring), Trapezoidal Shaped, Self-Locking I/O Connector	November-97	October-02	6
700D000		Sectional Specification for Discrete Contacts of Certified Quality (for Use in dc/Low Frequency Analog Applications and in Digital Applications Employing High Speed Data Rates)	January-98	January-03	6
710		Requirements Guide for Space Grade Electrical Connectors	October-97	October-02	6
700B000		Sectional Specification for Rectangular/Trapezoidal Connectors of Certified Quality	May-99	May-04	5
700BA00		Blank Detail Specification for Rectangular/Trapezoidal Connectors of Certified Quality	September-98	September-03	5
700A0AE		Detail Specification for Trapezoidal Connectors with Nonremovable Ribbon Cable Contacts on 1.27mm Pitch Double Row Used with Single Connector Attachments (SCA2)	January-00	December-04	4
700A0AF		Detail Specification for Trapezoidal Shielded Connector 0.8 mm Pitch Used with Very High Density Cable Interconnect (VHDCI)	July-00	June-05	4
700BAAD		Detail Specification for Shielded Rectangular Connectors for Universal Serial Bus Plus Power Connectors Series "A"	May-00	April-05	4
700BAAE		Detail Specification for Shielded Rectangular Connectors for Universal Serial Bus Plus Power Connectors Series "B"	May-00	April-05	4
616	A	Detail Specification for 2 Millimeter, Two-Part Connectors for Use with Printed Boards and Backplanes	November-02	November-07	1
622	A	Glossary of Electrical Connector Related Terms	August-07	August-12	-4
700A0AC		DETAIL SPECIFICATION FOR 1.00 MM PITCH, 88 CIRCUIT DRAM MEMORY CARD INTERCONNECT SYSTEM	August-96	Ausust-01	

- Approved to be obsoleted or rescinded

### Socket Specifications Past Due for 5-Year Review

EIA	Rev	Title	Date of last issue	5 Year due date	Years past due
CB-5-1		Recommended Test Procedure for Semiconductor Thermal Dissipating Devices-Addendum to CB5	May-71	April-76	33
540ADAA		Detail Specification for Adaptor-Carrier Quad Flatpack to Pin Grid Array Sockets for Use in Electronic Equipment	February-92	January-97	12
540FA00	A	Blank Detail Specification for Multi-Package Module Sockets for Use in Electronic Equipment	April-92	March-97	12
540FAAA		Detail Specification for Multi-Package 100 Mil Pitch, Vertical Mounting Format Module Sockets for Use in Electronic Equipment	January-92	December-96	12
540FAAB		Detail Specification for Multi-Package 100 Mil Pitch, Angled Mounting Format Module Sockets for Use in Electronic Equipment	January-92	December-96	12
540FAAC		Detail Specification for Multi-Package 50 Mil Pitch, Vertical Mounting Format Module Sockets for Use in Electronic Equipment	January-92	December-96	12
540FAAD		Detail Specification for Multi-Package 50 Mil Pitch, Angled Mounting Format Module Sockets for Use in Electronic Equipment	January-92	December-96	12
540DB00		Blank Detail Specification for Decoupling Capacitor Dual In-Line Package Sockets	June-93	December-97	11
540DB00		BLANK DETAIL SPEC FOR DIP SOCKETS W/DECOUPLING CAP	June-93	June-98	11
540E000		Sectional Specification for Round-Style Sockets for Use in Electronic Equipment	February-93	February-98	11
540G000		Sectional Specification for Burn-In Sockets for Use in Electronic Equipment	January-93	December-97	11
540GA00		Blank Detail Specification for Burn-In Sockets for Chip Carrier Packages with Molded Carrier Rings for Use in Electronic Equipment	January-93	December-97	11
540GAAA		Detail Specification for Burn-In Sockets for Chip Carrier Packages with Molded Carrier Rings for Use in Electronic Equipment	January-93	December-97	11
540DBAA		Detail Specification for Decoupling Capacitor Dual In-Line Package Sockets for Use in Electronic Equipment	January-94	December-98	10
675		Specification for Small Form Factor 33.0 mm (1.3 in) Disk Drives	January-96	December-00	8
540BAAA	A	Detail Specification for Mechanically Actuated (Zero and Low Insertion Force) Sockets for Pin Grid Array Devices with 2.54 mm X 2.54 mm (0.1 in X 0.1 in) Spacing for Use in Electronic Equipment	August-96	August-01	7
677		Specification for Small Form Factor Power Connector Pin Dimensions	June-97	June-02	7
IS-701		Production Ball Grid Array (BGA) Socket Test Specification	July-96	July-01	7

**Socket Specifications Past Due for 5-Year Review**

EIA	Rev	Title	Date of last issue	5 Year due date	Years past due
540CAAC	A	Detail Specification for 2 Pole, 10 A Relay Sockets	November-98	November-03	5
740		Specification for Small Form Factor 88.9 mm (3.5 in) Disk Drives	July-99	June-04	5
540CAAD	A	Detail Specification for 2 Pole, 5 A Relay Sockets	August-99	August-04	4
540CAAE	A	Detail Specification for 3 Pole, 10 A Relay Sockets	August-99	August-04	4
540HA00		Blank Detail Specification for Burn-In Sockets Used with Ball Grid Array Devices for Use in Electronic Equipment	May-00	April-05	4
540HAAA		Detail Specification for Burn-In Sockets Used with Ball Grid Array Devices for Use in Electronic Equipment	June-00	May-05	4
540J000		Sectional Specification for Battery Holders for Use in Electronic Equipment	May-00	April-05	4
540J0AA		Detail Specification for Cylindrical Battery Holders, Standard Profile, for Use in Electronic Equipment	May-00	April-05	4
773		Check List for Document Development and Revision	May-00	April-05	4
540J0AB		Detail Specification for Coin Cell Battery Holders for Use in Electronic Equipment	June-01	May-06	3
741		Specification for Small Form Factor 133.35 mm (5.25 in) Disk Drives	May-01	April-06	3
540B0AA	A	Detail Specification for Production Ball Grid Array (BGA) High Pin Count (1089 Pins and Greater) Socket for Use in Electronic Equipment-Revision	October-01	September-06	2
676	A	Specification for Parallel 1.8 inch Drive Form Factor (78 millimeter x 54 millimeter)	June-06	June-11	-2
674	A	Specification for Dimensions and Connectors Locations of Small Form Factor 45 millimeter (1.8 inch) Disk Drive	August-06	August-11	-3

- Approved to be obsoleted or rescinded
- Duplicate listing

The unanimously agreed to obsolete all Generic, Sectional and Blank Details Specifications. Carl Fritz has agreed to be project leader. It was moved by Don Chambers and seconded by Bob Druckenmiller to obtain a project number and send out on SP ballot. If there no objections or negative received the document shall be sent to EIA to rescind (withdraw). The motion was unanimously approved.

It was moved by Frank Ruffino and seconded by Ed Wypasek to obtain a project number and send out all detail specifications that are more than 10 years past due to have them “Stabilized” on an SP ballot. If there no objections or negatives received the document shall be sent to EIA to be listed as “Stabilized”. The motion was unanimously approved.

It was note that all specifications labeled as “Stabilized” are NOT subject to the 5-year review process in the future; however, they may be revised at anytime.

### Unknown Connector Documents

EIA	Rev	Title	Date of last issue	5 Year due date	Years past due	Comments
51		EMISSION LIMITATION AM BROADCAST TRANSMISSION	September-88	August-93		Number unidentifiable
5810000		GENERIC SPEC RECTANGULAR CONNECTOR FOR FREQUENCIES BELOW 3 MHZ				Number unidentifiable
5880000		GEN SPEC PRINTED BD CONNECTORS OF ASSESSED QUALITY				Number unidentifiable
437-1		ADDENDUM NO. 1 TO EIA-437 BASIC SENSITIVE SWITCHES	September-78	August-83		Number unidentifiable
437-2			May-78	April-83		RESCINDED 9/25/89
437-3			September-78	August-83		RESCINDED 9/25/89
437-4			September-89	August-94		RESCINDED 9/25/89
437-5		20 AMP DOUBLE BREAK SENSITIVE SWITCHES	March-81	February-86		Number unidentifiable
437-6		15 AMP DOUBLE BREAK SENSITIVE SWITCHES	March-81	February-86		Number unidentifiable
437-7		10 AMP DOUBLE SENSITIVE SWITCHES	June-80	May-85		Number unidentifiable
437-8		8 AMP DOUBLE SENSITIVE SWITCHES	June-80	June-85		Number unidentifiable
64		INTERIM STD, 2MM TWO-PART CONN FOR PRINT WIRING BD	March-91	March-96		Number unidentifiable
700A000		SECT SPEC FOR PRINTED BOARD CONNECTORS ESSENTIALLY BELOW 3MHZ				No record that specification was ever issued
700A0AG		DT SP TRAPEZOIDAL PIN-AND-SOCKET CONN FIBER CHANNEL APPLICATIONS				No record that specification was ever issued
700AAAA		DT SP 1.27 mm PITCH RIBBON CONTACT TRAPEZOIDAL SHIELDED I/O CONNC				No record that specification was ever issued
700BAAA		CONNECTOR ELECT RECTANGULAR SCOOP-PROOF LOW FORCE SUBMINIATURE				No record that specification was ever issued
700BAAB		CONNECTORS, ELECTRICAL, RECTANGULAR, BLIND-MATE, SCOOP-PROOF				No record that specification was ever issued
700BAAC		DT SP BLIND-MATE, SCOOP PROOF EVA LOW EARTH ORBIT LEO CONNECTOR				No record that specification was ever issued
700D0AA		HIGH DENSITY TUNING FORK COMPONENTS				No record that specification was ever issued
700DA00		DISCRETE CONTACT BLANK DETAIL SPECIFICATION				No record that specification was ever issued

**Unknown Socket Documents**

<b>EIA</b>	<b>Rev</b>	<b>Title</b>	<b>Date of last issue</b>	<b>5 Year due date</b>	<b>Years past due</b>	<b>Comments</b>
540B0AB		Low Pin Count BGA				Sent letter to EIA to cancel project on 13 May 2008
540D0AA		DET. SPEC - SOCKETS FOR DUAL...PACKAGES	January-90	January-95		No record that specification was ever issued
540F0AG		DETAIL SPEC-SMALL OUTLINE DIMM DUAL-IN-LINE MEMORY MODULE SOCKETS				No record that specification was ever issued
540FAAE		DT SP DUAL IN-LINE MEMORY (DIMM) SOCKETS 1.27 MM VERTICAL MOUNT				No record that specification was ever issued
540FAAF		DT SP 8-BYTE 168 POSITION DUAL IN-LINE MEMORY MODULE SOCKET 1.27				No record that specification was ever issued
540JAAA		DT SP BURN-IN SOCKETS USE W/BALL GRID ARRAY DEVICE USE IN ELEC EQ				No record that specification was ever issued

**F. Obsolete or rescind all Generic, Sectional and Blank Detail Specifications (Carl Fritz)**

The unanimously agreed to obsolete all Generic, Sectional and Blank Details Specifications. Carl Fritz has agreed to be project leader. It was moved by Don Chambers and seconded by Frank Ruffino to obtain a project number and send out on SP ballot.

**G. SP-5193, EIA-7000000, EIA-700B000, EIA-700BA00, EIA-700C000, EIA-700D000, EIA-540DB00, EIA-540E000, EIA-540FA00, EIA-540G000, EIA-540GA00, EIA-540HA00 and EIA-540J000 “Electrical Connector and Socket Specifications” (Carl Fritz)**

Carl reported that he sent memo (mccwil399) to EIA for EDEC ballot to rescind (withdraw) the listed specifications on 2 December 2009.

- Received the following letter (SP-5193 Withdrawal) from EIA on 22 January 2010:

MEMO TO; Mary Weldon  
ANSI

FROM: Cecelia M. Yates  
Engineering Services Admin.

RE: Withdrawal of ANSI Accredited Standards

In accordance with your ANSI paragraph 4.2.1.3.2 of Essential Requirements, EIA/ECA is notifying you the following standards have been withdrawn.

This is applicable to EIA-7000000, EIA-700BA00, EIA-700C000, EIA-700D000, and EIA-540FA00

- Received the following letter and similar e-mail on the Specification highlighted in yellow from EIA on 18 February 2010:

**From:** Mary Weldon [mailto:MWELDON@ansi.org]

**Sent:** Thursday, February 18, 2010 3:42 PM

**To:** Cecelia Yates

**Subject:** Acknowledgement of Request for Withdrawal of ANSI/EIA 540GA00-1993 (R2001) in Standards Action: 2/26/2010

Withdrawal by Accredited Standards Developer

ANSI EIA Standards

In accordance with ANSI Essential Requirements section 4.2.1.3.2, Withdrawal by an Accredited Standards Developer, the following American National Standard(s) are hereby withdrawn:

ANSI/EIA 540GA00-1993 (R2001), Blank Detail Specification for Burn-In Socket for Chip Carrier Packages with Molded Carrier Rings for Use in Electronic Equipment

Direct inquiries to: Cecelia Yates, at cyates@ecaus.org

This is to acknowledge receipt of your request for an announcement in Standards Action by ANSI to withdraw the standard listed above. The issue of Standards Action in which the announcement will appear is: 2/26/2010

This is applicable to 700B000, 540HA00, 540J000, 540E000, 540DB00, 540GA00 and 540G000.

## H. Stabilize Listed Specification

EIA-	Current Revision	Title
270		Tools, Crimping, Solderless Wiring Devices - Recommended Procedures for User Certification
280	C	Solderless Wrapped Electrical Connections
297	A	Cable Connectors for Audio Facilities for Radio Broadcasting-Correction Sheet
380	A	Electrical Connectors, Small Contact Standard for
406		General Document for Connectors, Electric, Printed-Wiring Board-IPC-C-405A
429		Connectors, Electrical Flat Cable Type-IPC FC-218B
540ADAA		Detail Specification for Adaptor-Carrier Quad Flatpack to Pin Grid Array Sockets for Use in Electronic Equipment
540FAAA		Detail Specification for Multi-Package 100 Mil Pitch, Vertical Mounting Format Module Sockets for Use in Electronic Equipment
540FAAB		Detail Specification for Multi-Package 100 Mil Pitch, Angled Mounting Format Module Sockets for Use in Electronic Equipment
540FAAC		Detail Specification for Multi-Package 50 Mil Pitch, Vertical Mounting Format Module Sockets for Use in Electronic Equipment
540FAAD		Detail Specification for Multi-Package 50 Mil Pitch, Angled Mounting Format Module Sockets for Use in Electronic Equipment
540GAAA		Detail Specification for Burn-In Sockets for Chip Carrier Packages with Molded Carrier Rings for Use in Electronic Equipment
CB-5-1		Recommended Test Procedure for Semiconductor Thermal Dissipating Devices-Addendum to CB5
IS-47		Contact Termination Finish Standard for Surface Mount Devices
IS-84		Interim Detail Specification for 2.5 mm Two Part Connector for Use in Electronic Equipment

Sent memo (mccwil395) to EIA to obtain a project number to “Stabilize” the following specifications on 28 October 2009:

*Sent the following e-mail to Ed Mikoski on 2 October 2010 following the meeting:*

*Greetings Ed, Thank you again for a good meeting. I have attached the memorandum that I sent Cecelia last year to "Stabilize" the Specifications listed. Cecelia was not able to process the request for project numbers at that time because there is no clear understanding on how to proceed. Since this is the first attempt to "Stabilize" it was not know if I need a PN for every Specification on the list or just one PN to cover all, as we are currently doing for reaffirmations. Once this is resolved, and I get a PN, I prepare the request letter to "Stabilize" the listed documents. Kind regards, Carl*

## **6. SFF COMMITTEE PROJECTS**

### **6.1 Active Projects (Frank Ruffino)**

#### **A. SP or PN-5190, EIA-964, Detail Specification for QSFP+ Copper and Optical Modules (formerly SFF-8436) (Frank Ruffino)**

Carl reported that he sent cover memo (mccwil381 and PINS form to EIA requesting a project number on 11 June 2009 on behalf of Frank Ruffino.

Received project numbers 11 June 2009.

#### **B. SP or PN-5191, EIA-965, Detail Specification for Mini Multilane Shielded Integrated Connector (formerly SFF-8642) (Frank Ruffino)**

Carl reported that he sent cover memo (mccwil381 and PINS form to EIA requesting a project number on 11 June 2009 on behalf of Frank Ruffino.

Received project numbers 11 June 2009.

- Carl reported that he received draft from Frank Ruffino on 2 July 2010. I replied to Frank on 2 July 2010 as follows:

Frank a quick check tells me that 95% is there. The only thing that I see missing is a test sequence. All that is there is the electrical, mechanical, and environmental criteria. I already got a project number and specification number assigned in June 2009. The Project number is 5191 and the Specification number is EIA-965. If we had a sequence and number of specimens to be tested I think it could fly as a ballot. What do you want me to do with it? Carl

- Carl sent Frank a draft dated 17 September 2010 that contains the new testing paragraph 7.

#### **C. SP or PN-5201, EIA-966, Specification for Unshielded Dual Port Serial Attachment Connector (formerly SFF-8482) (Frank Ruffino)**

Sent cover memo (mccwil396 and PINS form to EIA requesting a project number on 10 November 2009 on behalf of Frank Ruffino.

Received project numbers 10 November 2009 as follows.

Sent draft to Frank Ruffino on 12 November 2009 to review.

**D. SP or PN-5202, EIA-967, Specification for Micro Serial Attached SCSI (SAS) Connector (formerly SFF-8486) (Frank Ruffino)**

Sent cover memo (mccwil396 and PINS form to EIA requesting a project number on 10 November 2009 on behalf of Frank Ruffino.

Received project numbers 10 November 2009 as follows:.

Sent draft to Frank Ruffino on 12 November 2009 to review.

**6.2 Future Projects (Frank Ruffino)**

<b>SFF designation</b>	<b>Title</b>	<b>Status</b>
SFF-8079	SFP Rate and Application Selection	
SFF-8087	Mini Multilane Series Connector: Unshielded	
SFF-8088	Mini Multilane Series Connector: Shielded	
SFF-8089	SFP Rate and Application Codes	
SFF-8100	Suite of <2.5" Form Factor Specifications	
SFF-8200	Suite of 2.5" Form Factor Specifications	
SFF-8300	Suite of 3.5" Form Factor Specifications	
SFF-8416	Measurement & Performance Requirements for HPEI Bulk Cable	
SFF-8431	SFP+'	
SFF-8432	IPF (Improved Pluggable Formfactor	
SFF-8433	IPF (Improved Pluggable Formfactor) Cage	
SFF-8436	QSFP Copper and Optical Transceivers	Received project number 5190 (EIA-964)
SFF-8448	SAS Sideband Utilization	
SFF-8460	HSS Backplane Design Guidelines	
SFF-8482	Internal Serial Attachment Connector	Received project number 5201 (EIA-966). Draft prepared 12 Nov 10
SFF-8484	4-Wide Internal Serial Attachment Connector	
SFF-8485	Serial GPIO (SGPIO) Bus	
SFF-8486	Micro SAS Connector	Received project number 5202 (EIA-967). Draft prepared 12 Nov 10
SFF-8500	Suite of 5.25" Form Factor Specifications	
SFF-8642	Mini Multilane Series: Shielded Integrated Connector	Received project number 5191 (EIA-965). Draft prepared 17 Sep 10.

## **7. LIASION REPORTS**

### **A. DLA LAND AND MARITIME report (formerly DSCC) including Army, USAF, Navy; except NAVAIR (Ed Wypasek)**

Ed Wypasek presented his report. Ed indicated that at the end of the report is the MIL-DTL-38999 report from Ralph Antonelli. After reviewing for new projects, I highlighted the ones I would like to have the committee to glance at and start a project. I never proposed a project, but Ralph informed me that the committee will need to approve to get one started. I'll have some questions. This item has been included with the work items in CE-2.1. Carl indicated that he would provide guidance in the development of any new TP's.

**(See Attachment No. 4 for DLA LAND AND MARITIME (formerly DSCC report).**

### **B. NAVAIR (Dwight Tabit)**

Carl submitted the NAVAIR report submitted by Dwight Tabit as follows:

**(See Attachment No. 5 for NAVAIR report).**

### **C. SAE (Dave Bouzek)**

David reported that there is some movement within SAE AE-8C1 committee to allow palladium plating as a substitute for gold. This was the first meeting where Patrick Oakes was the chairman and Bobby Crumb is the vice chairman. The next meeting would be held the week of 25 October 2010 in Savannah, GA.

**(See Attachment No. 6 for SAE report).**

### **D. ASTM (Frank Ruffino)**

Frank reported that the next meeting will be held the 9 November 2010 in St. Louis, MO.

## **8. OTHER BUSINESS**

### **A. WEB Database Review (Carl Fritz and Frank Ruffino)**

Ed Mikoski provided the committee with an updated copy of the data base.

## **9. NEW BUSINESS**

Carl brought up the possibility of taking on the responsibility of converting MIL-STD-202 to EIA test procedures, similar to what was done with MIL-STD-1344. This was as a result of seeing recently published EIA-717A referencing MIL-STD-202 test procedures. Ed Wypasek will put out some feelers to see if the military would be receptive to us taking on the responsibility and adopting it as an EIA Standard as was done to MIL-STD-1344. Such a project would add work to the committee and possibly attract new members.

## **10. FUTURE MEETINGS**

Next meeting is tentatively scheduled for 3 - 4 May 2011 (preferred) 26- 27 April (optional) in Orlando, FL at the Hyatt Grand Cypress.

## **11. ADJOURNMENT**

The meeting was adjourned at 3:46 PM on 29 September 2010.

Respectfully submitted,

Frank Ruffino, Chairman CE-2.0

Prepared by  
Carl Fritz, Secretary CE-2.0